

ABSTRACT OF THE DISCLOSURE

Double-sided interposer assemblies and methods for forming and using them. In one example of the invention, an interposer comprises a substrate having a first surface and a second surface opposite of said first surface, a first plurality of contact elements disposed on said first side of said substrate, and a second plurality of contact elements disposed on said second surface of said substrate, wherein said interposer connects electronic devices via said first and said second plurality of contact elements.

[illegible]